



**80L MQFP**

**Plastic**

**Intern Code: MM80N**

**Company** : X-FAB Semiconductor Foundries AG  
**Date Released** : 29.May.2015  
**Type** : XVDTC2\_11.1  
**Die Size [mm]** : 3.772 x 3.772  
**Cavity [mil]** : 252 x 252 UP  
**Bond Wire** : 1.0 Au  
**Pinfile** : XVDTC2\_11\_1.Bonding.pin 29.May.2015 12:01:34  
**PAD Type/Min X/ Y / Pitch** : Typ \*/ 53um / 66um / 110um \* Types of bonded pads are different

**Approvals:**

**Engineer (Date/Sign) :** \_\_\_\_\_

**PKG/QA. (Date/Sign) :** \_\_\_\_\_

**Ref # :** \_\_\_\_\_

**Engineering**

